



N 沟道增强型场效应晶体管
N-CHANNEL MOSFET
FHU70N03C/FHD70N03C

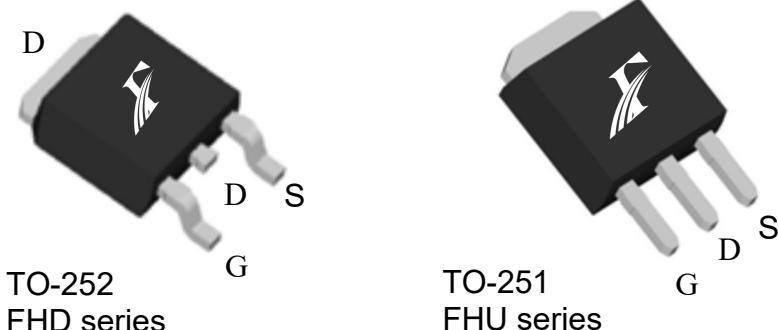
主要参数 MAIN CHARACTERISTICS

ID	70 A
VDSS	30 V
Rdson-typ (@Vgs=10V)	6.3mΩ
Rdson-typ (@Vgs=4.5V)	10.7mΩ
Qg-typ	14nC

用途 APPLICATIONS

在计算、服务器和全光网上 的DC-DC转换电路	DC/DC Converters in Computing, Servers, and POL
便携式设备的电池管理	Battery management in portable equipment

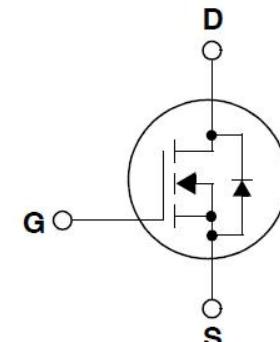
封装形式 Package



产品特性 FEATURES

低栅极电荷	Low gate charge
低 Crss (典型值 45pF)	Low Crss (typical 45pF)
开关速度快	Fast switching
100% 经过热阻测试	100% △DVDS tested
100% 经过雪崩测试	100% avalanche tested
100% 经过 Rg 测试	100% Rg tested
高抗 dv/dt 能力	Improved dv/dt capability
RoHS 产品	RoHS product
Trench 工艺	Trench technology

等效电路 Equivalent Circuit



绝对最大额定值 ABSOLUTE RATINGS (Tc=25°C)

项目 Parameter	符号 Symbol	数值 Value		单位 Unit
		FHU70N03C	FHD70N03C	
最高漏极-源极直流电压 Drain-Source Voltage	VDS	30		V
连续漏极电流* Drain Current -continuous *	I _D (T _c =25°C)	70		A
	I _D (T _c =100°C)	44.5		A
最大脉冲漏极电流 (注 1) Drain Current – pulse (note 1)	I _{DM}	280		A
最高栅源电压 Gate-Source Voltage	V _{GS}	±20		V
单脉冲雪崩能量 (注 2) Single Pulsed Avalanche Energy (note 2)	E _{AS}	32		mJ
雪崩电流 (注 1) Avalanche Current (note 1)	I _{AR}	8		A
重复雪崩能量 (注 1) Repetitive Avalanche Current (note 1)	E _{AR}	1.5		mJ
二极管反向恢复最大电压变化速率 (注 3) Peak Diode Recovery dv/dt (note 3)	dv/dt	5.0		V/ns
耗散功率 Power Dissipation	P _D (TC=25°C)	37.5		W
	-Derate above 25°C	0.25		W/°C
最高结温及存储温度 Operating and Storage Temperature Range	T _J , T _{STG}	-55~+175		°C
引线最高焊接温度 Maximum Lead Temperature for Soldering Purposes	T _L	300		°C

*漏极电流由最高结温限制

*Drain current limited by maximum junction temperature

电特性 ELECTRICAL CHARACTERISTICS

项目 Parameter	符号 Symbol	测试条件 Tests conditions	最小 Min	典型 Typ	最大 Max	单位 Units	
关态特性 Off -Characteristics							
漏一源击穿电压 Drain-Source Voltage	BVDSS	ID=250μA, VGS=0V	30	-	-	V	
击穿电压温度特性 Breakdown Voltage Temperature Coefficient	ΔBVDSS/Δ TJ	ID=250μA, referenced to 25°C	-	0.12	-	V/°C	
零栅压下漏极漏电流 Zero Gate Voltage Drain Current	Idss	VDS=30V, VGS=0V, TC=25°C	-	-	1	μA	
栅极体漏电流 Gate-body leakage current	IGSS (F/R)	VDS=30V, TC=125°C	-	-	100	μA	
		VDS=0V, VGS =±20V	-	-	±100	nA	
通态特性 On-Characteristics							
阈值电压 Gate Threshold Voltage	VGS(th)	VDS = VGS , ID=250μA	1.0	1.4	2.2	V	
静态导通电阻 Static Drain-Source On-Resistance	RDS(ON)	VGS =10V , ID=20A	-	6.3	8.0	mΩ	
		VGS =4.5V , ID=20A	-	10.7	13		
正向跨导 Forward Transconductance	gfs	VDS = 5V, ID=20A (note 4)	-	42	-	S	
动态特性 Dynamic Characteristics							
栅电阻 Gate Resistance	Rg	f=1.0MHz, VDS OPEN	-	-	20	Ω	
输入电容 Input capacitance	Ciss	VDS=15V, VGS =0V, f=1.0MHz	-	1140	-	pF	
输出电容 Output capacitance	Coss		-	400	-		
反向传输电容 Reverse transfer capacitance	Crss		-	45	-		
开关特性 Switching Characteristics							
延迟时间 Turn-On delay time	td(on)	VDS=15V, ID=20A, RG=3Ω VGS =10V (note 4, 5)	-	7	-	ns	
上升时间 Turn-On rise time	tr		-	13.5	-	ns	
延迟时间 Turn-Off delay time	td(off)		-	18.5	-	ns	
下降时间 Turn-Off Fall time	tf		-	4	-	ns	
栅极电荷总量 Total Gate Charge	Qg	VDS =15V , ID=20A , VGS =10V (note 4, 5)	-	14	-	nC	
栅一源电荷 Gate-Source charge	Qgs		-	3	-	nC	
栅一漏电荷 Gate-Drain charge	Qgd		-	2.5	-	nC	
漏一源二极管特性及最大额定值 Drain-Source Diode Characteristics and Maximum Ratings							
正向最大连续电流 Maximum Continuous Drain -Source Diode Forward Current	Is		-	-	70	A	
正向最大脉冲电流 Maximum Pulsed Drain-Source Diode Forward Current	ISM		-	-	280	A	
正向压降 Drain-Source Diode Forward Voltage	VSD	VGS=0V, Is=20A	-	0.9	1.3	V	
反向恢复时间 Reverse recovery time	trr	VGS=0V, Is=20A ,dI/dt=100A/μs (note 4)	-	12	-	ns	
反向恢复电荷 Reverse recovery charge	Qrr		-	20	-	nC	

热特性 THERMAL CHARACTERISTIC

项目 Parameter	符号 Symbol	FHU70N03C/FHD70N03C	单位 Unit
结到管壳的热阻 Thermal Resistance, Junction to Case	R _{th(j-c)}	4	°C/W
结到环境的热阻 Thermal Resistance, Junction to Ambient	R _{th(j-A)}	50	°C/W

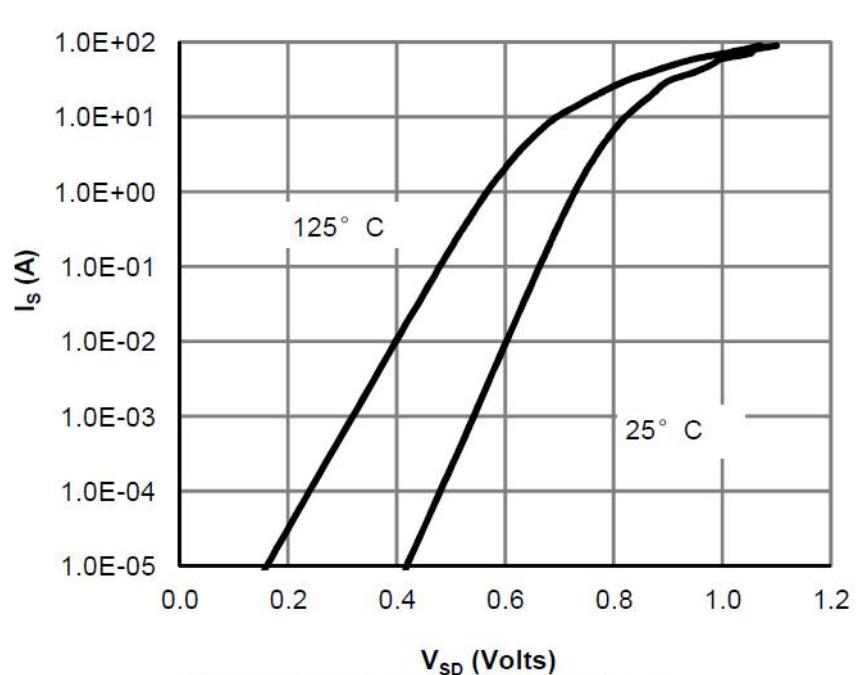
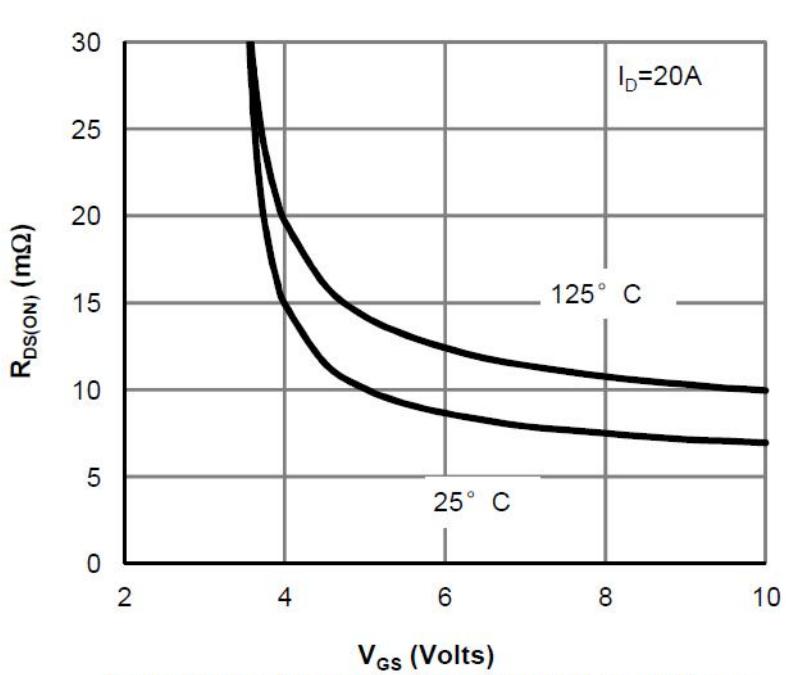
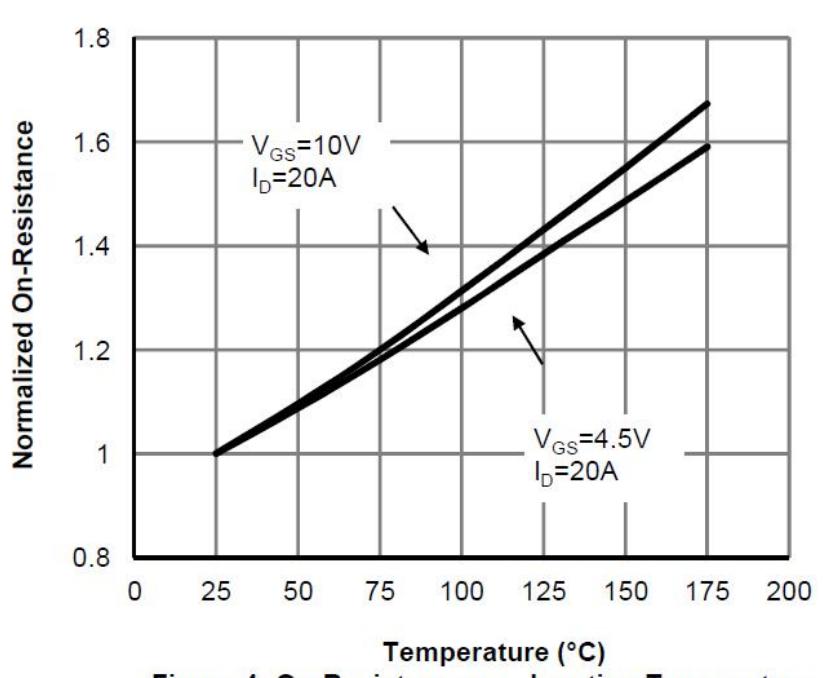
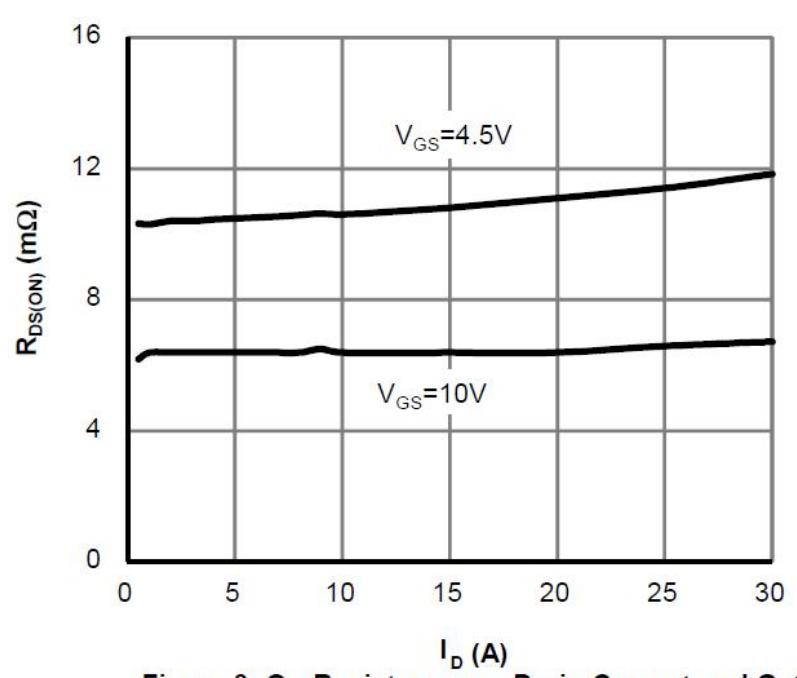
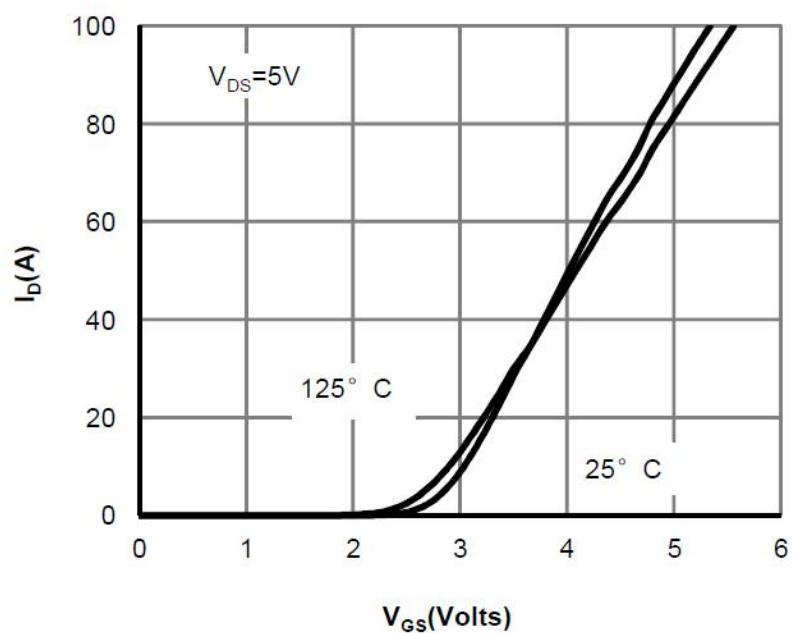
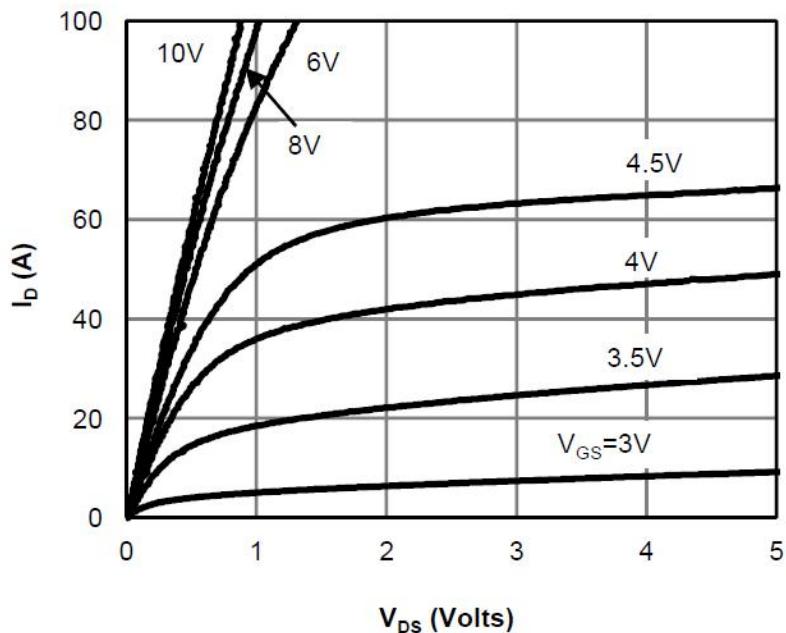
注释:

- 1: 脉冲宽度由最高结温限制
- 2: L=1mH, I_{AS}=8A, V_{DD}=25V, R_G=25 Ω, 起始结温 T_J=25°C
- 3: I_{SD} ≤ 70A, di/dt ≤ 100A/μs, V_{DD} ≤ BV_{DSS}, 起始结温 T_J=25°C
- 4: 脉冲测试: 脉冲宽度 ≤ 300μs, 占空比≤2%
- 5: 基本与工作温度无关

Notes:

- 1: Pulse width limited by maximum junction temperature
- 2: L=1mH, I_{AS}=8A, V_{DD}=25V, R_G=25 Ω, Starting T_J=25°C
- 3: I_{SD} ≤ 70A, di/dt ≤ 100A/μs, V_{DD} ≤ BV_{DSS}, Starting T_J=25°C
- 4: Pulse Test: Pulse Width ≤ 300μs, Duty Cycle≤2%
- 5: Essentially independent of operating temperature

特性曲线 Typical Characteristics



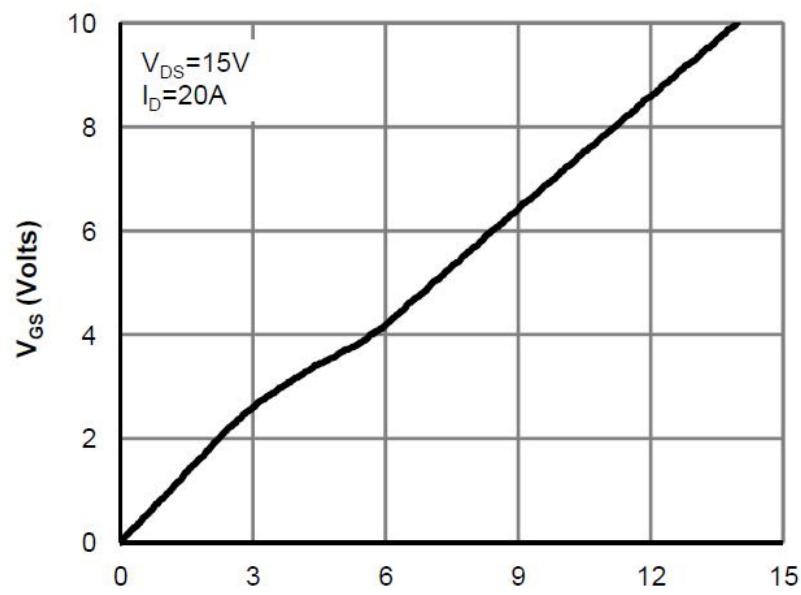


Figure 7: Gate-Charge Characteristics

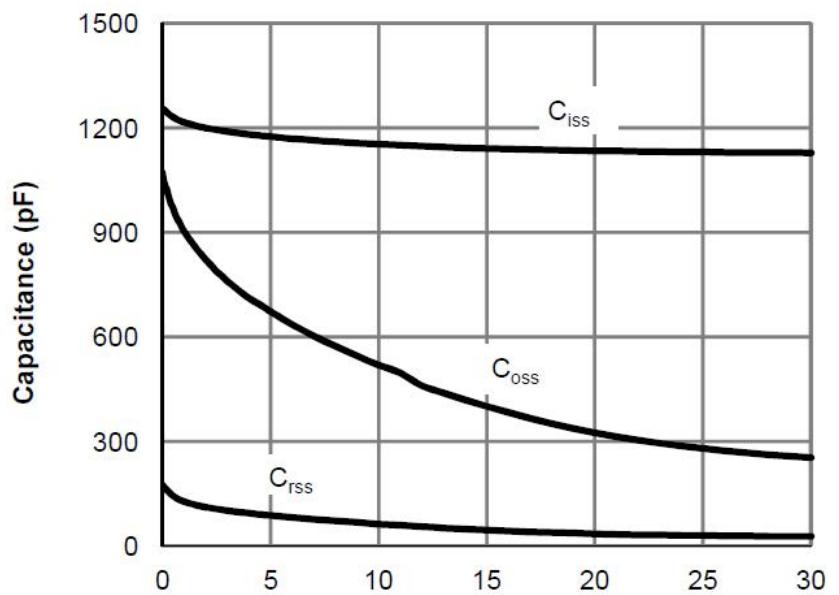


Figure 8: Capacitance Characteristics

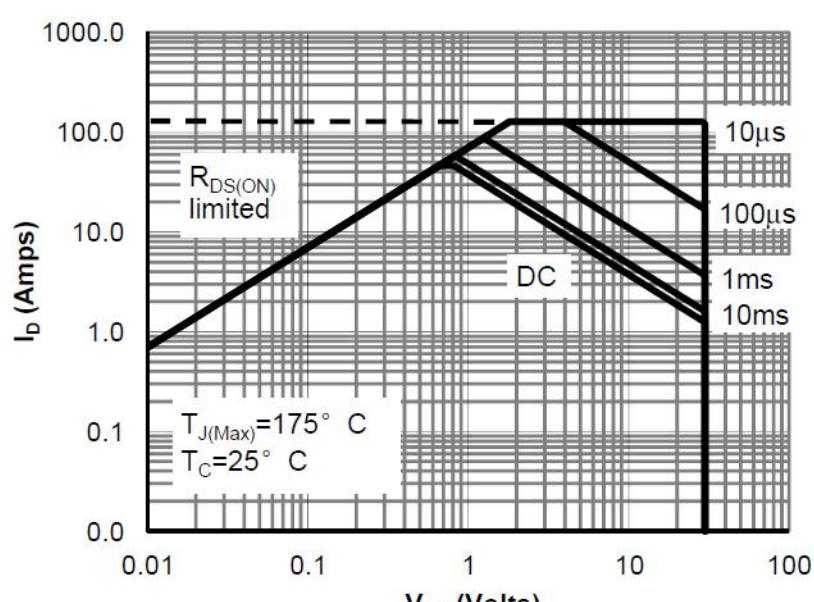


Figure 9: Maximum Forward Biased Safe Operating Area

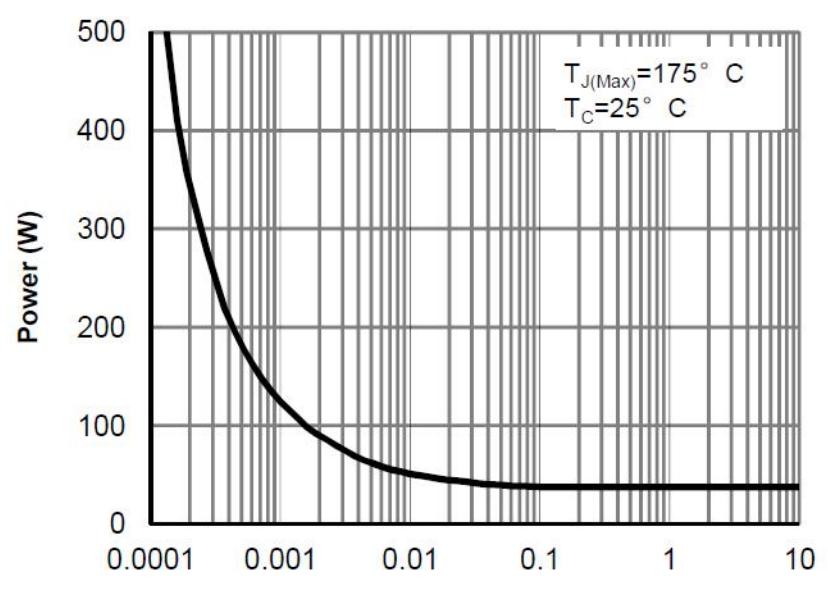


Figure 10: Single Pulse Power Rating Junction-to-Case

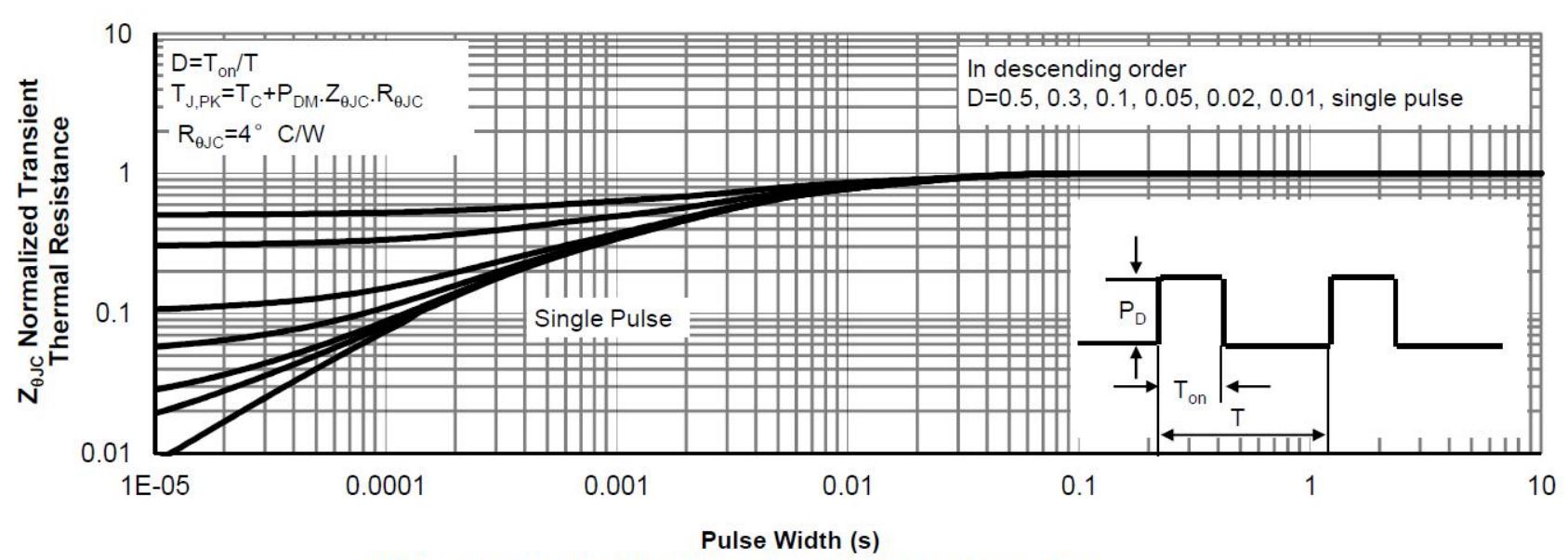
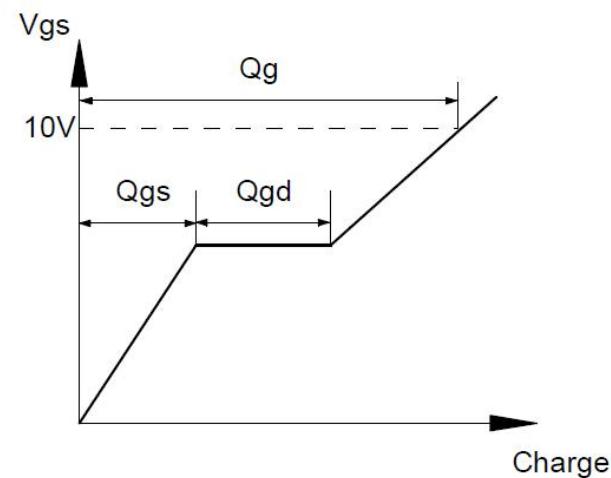
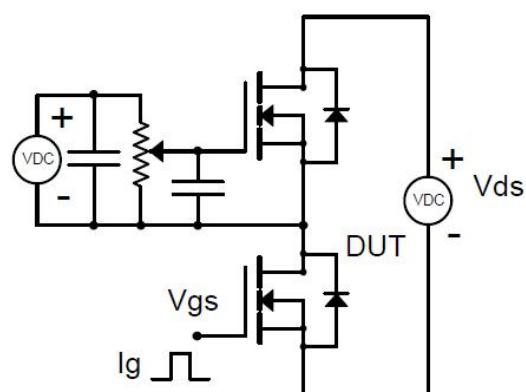
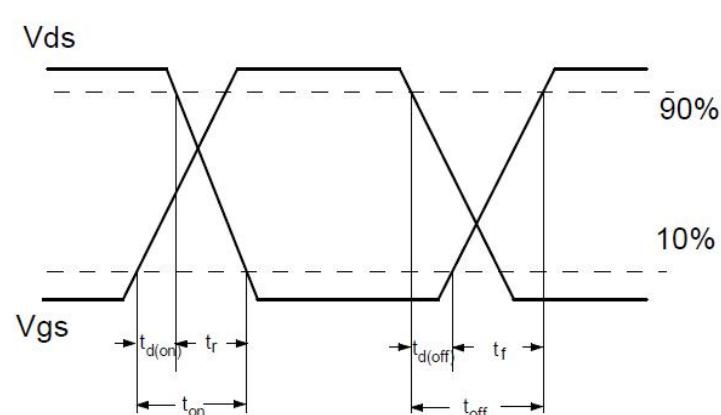
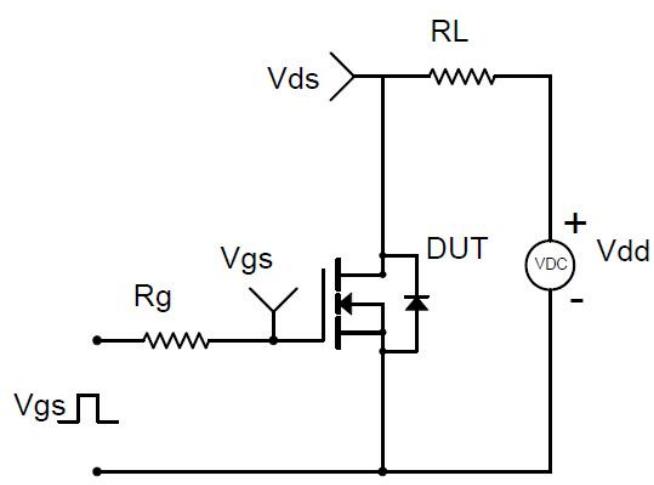


Figure 11: Normalized Maximum Transient Thermal Impedance

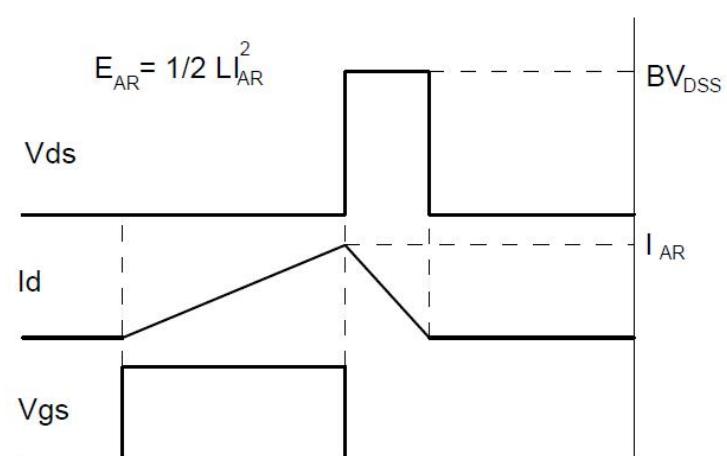
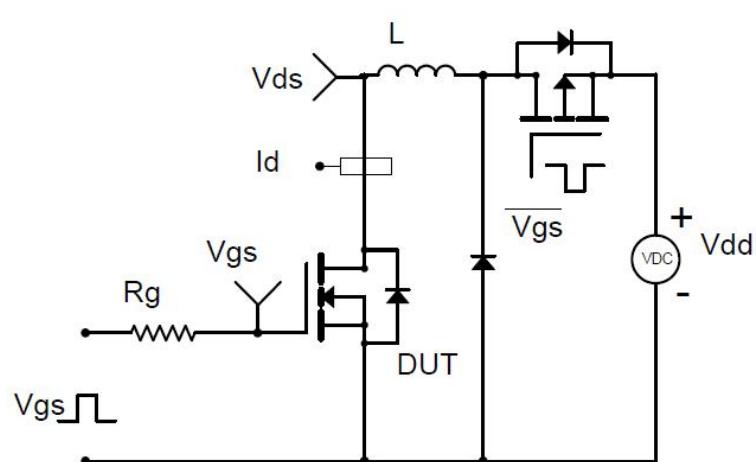
Gate Charge Test Circuit & Waveform



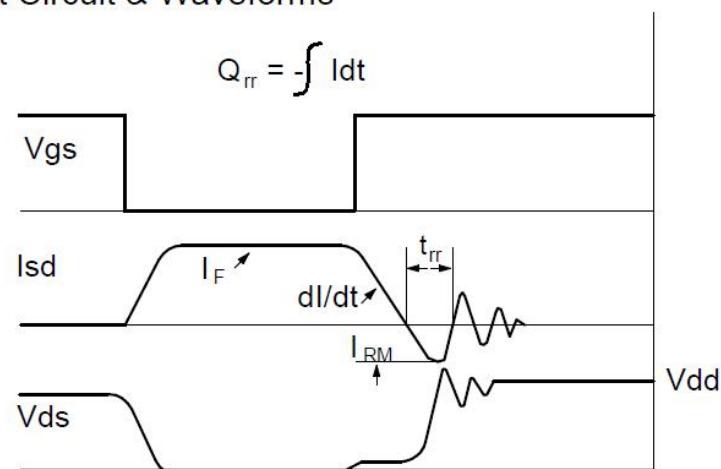
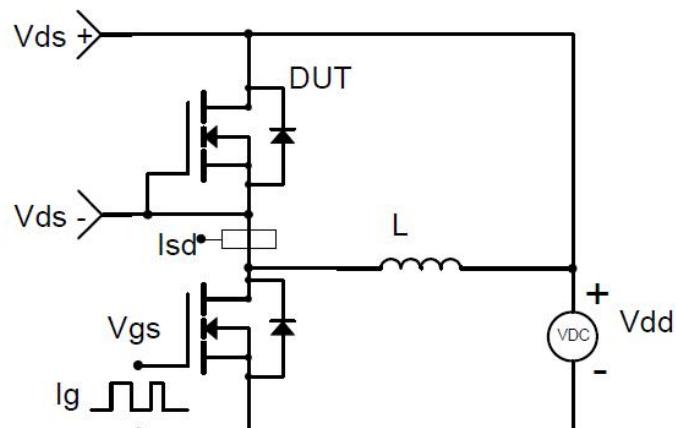
Resistive Switching Test Circuit & Waveforms



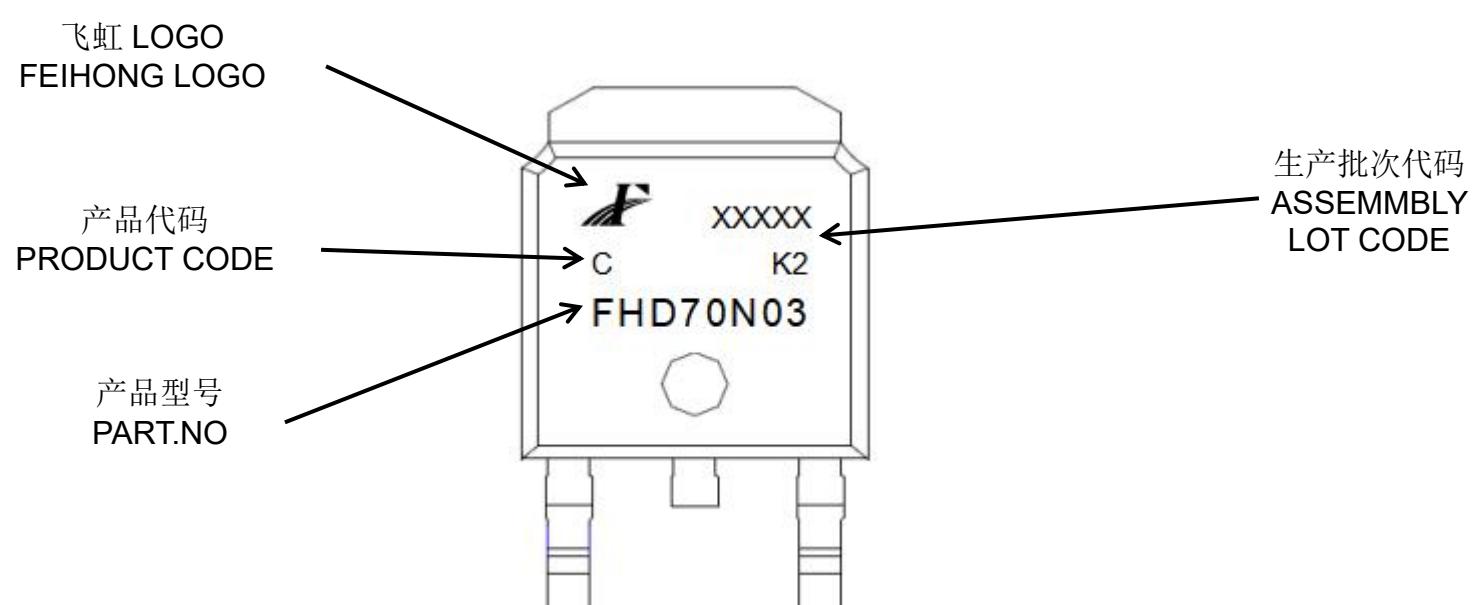
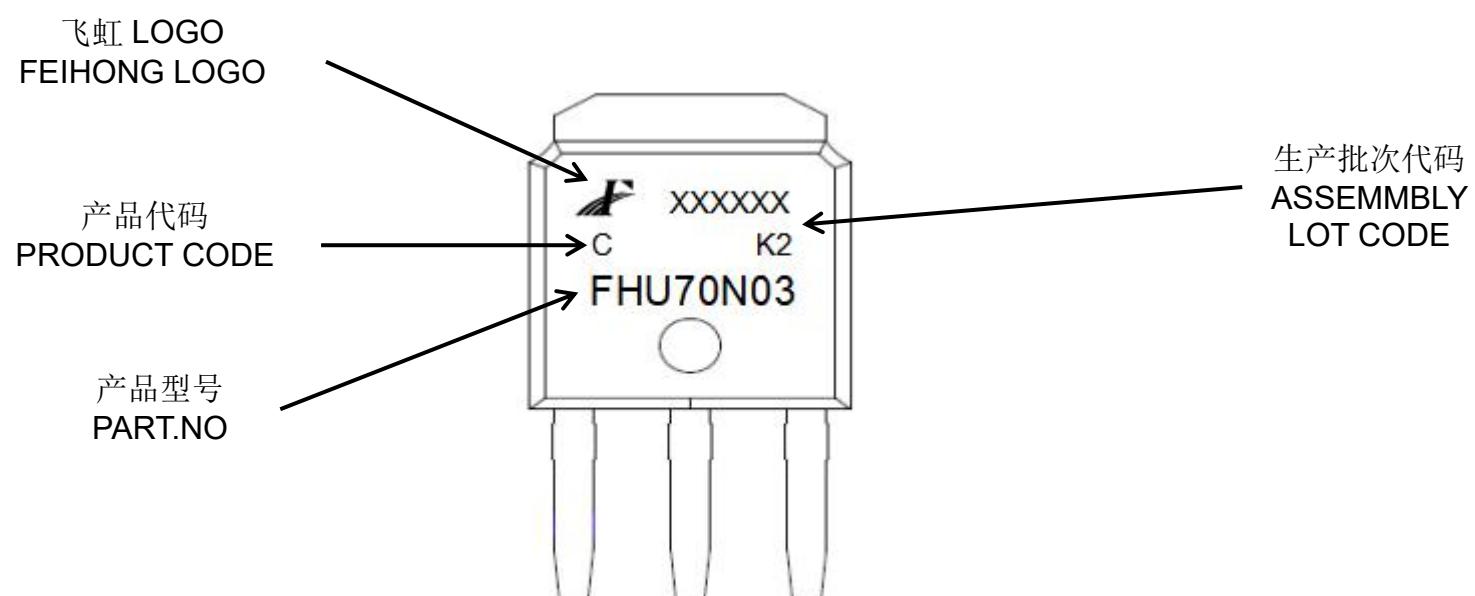
Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



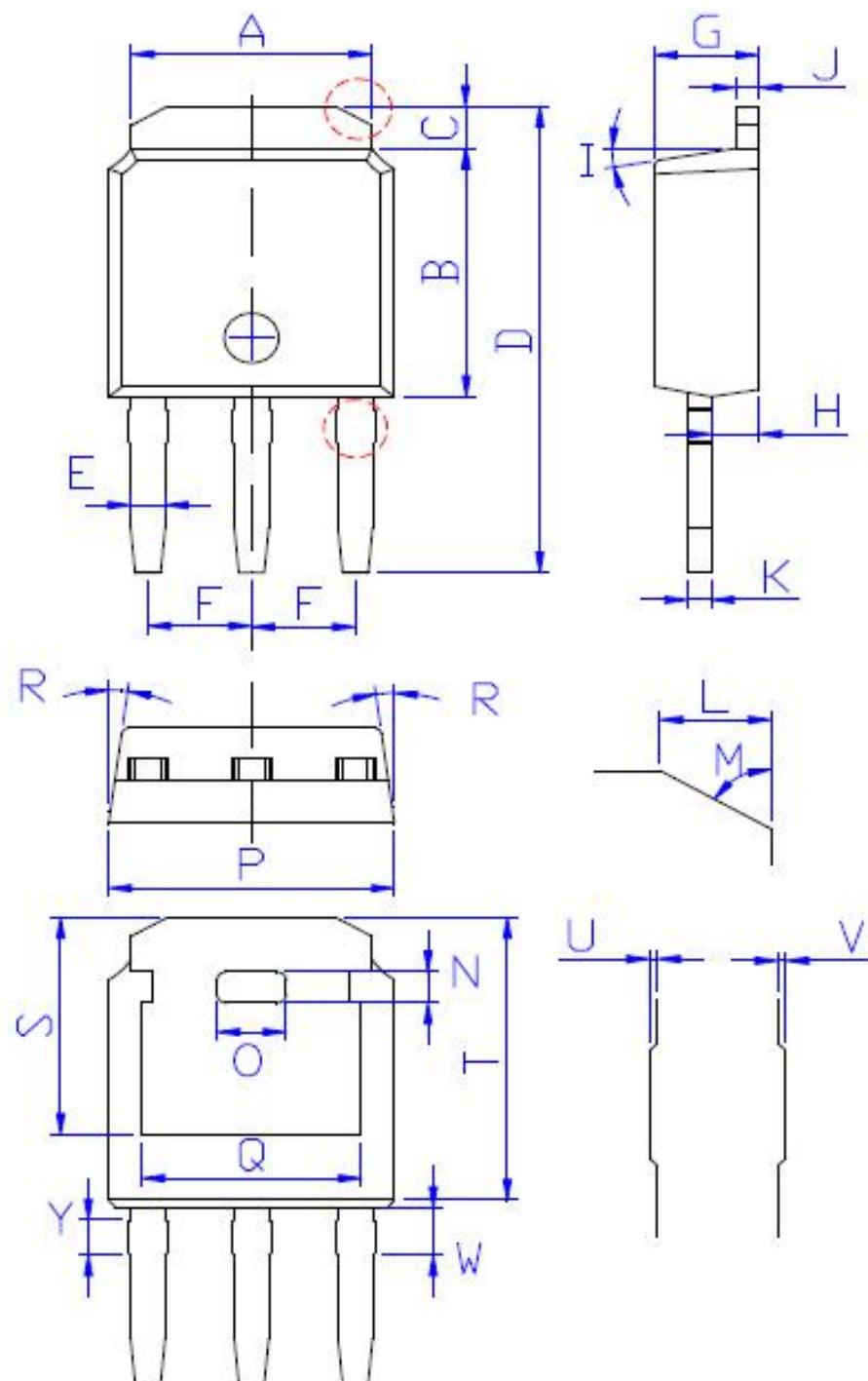
印记 Marking:



外形尺寸:

Package Dimension:

TO-251



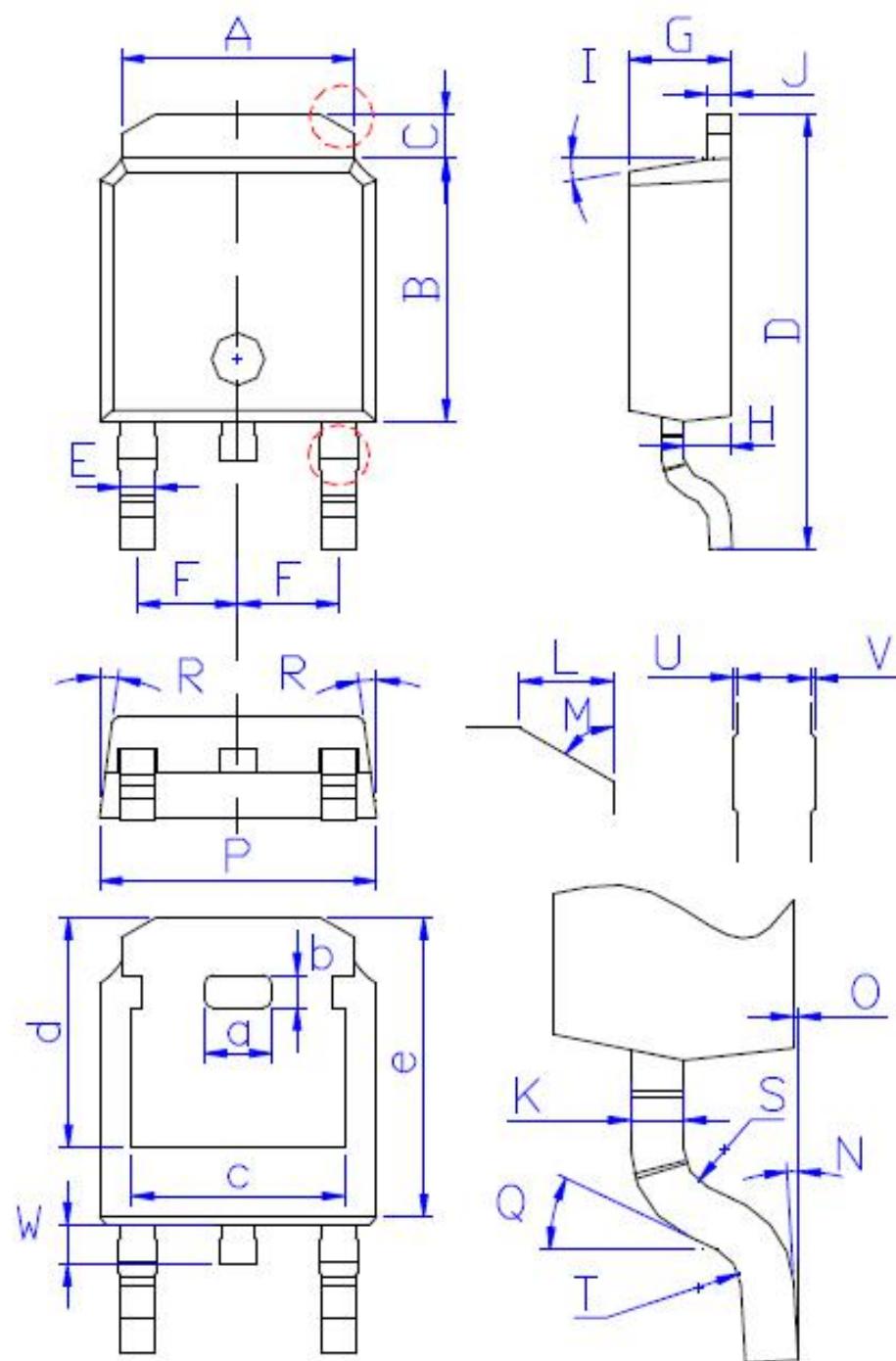
DIM	MILLIMETERS
A	5.34±0.30
B	6.00±0.30
C	1.05±0.30
D	11.31±0.30
E	0.76±0.15
F	2.28±0.15
G	2.30±0.30
H	1.06±0.30
I	(4-10)°
J	0.51±0.15
K	0.52±0.15
L	0.80±0.30
M	60°
N	0.75±0.30
O	1.80±0.30
P	6.60±0.30
Q	4.85±0.30
R	(4-8.5)°
S	5.30±0.30
T	6.90±0.30
U	0.05±0.05
V	0.05±0.05
W	1.15±0.25
Y	0.85±0.25

(Unit: mm)

外形尺寸:

Package Dimension:

TO-252



DIM	MILLIMETERS
A	5.34±0.30
B	6.00±0.30
C	1.05±0.30
D	9.95±0.30
E	0.76±0.15
F	2.28±0.15
G	2.30±0.30
H	1.06±0.30
I	(4-10)°
J	0.51±0.15
K	0.52±0.15
L	0.80±0.30
M	60°
N	(0-10)°
O	0.05±0.05
P	6.60±0.30
Q	25°
R	(4-8.5)°
S	R0.40
T	R0.40
U	0.05±0.05
V	0.05±0.05
W	0.90±0.30
a	1.80±0.30
b	0.75±0.30
c	4.85±0.30
d	5.30±0.30
e	6.90±0.30

(Units: mm)